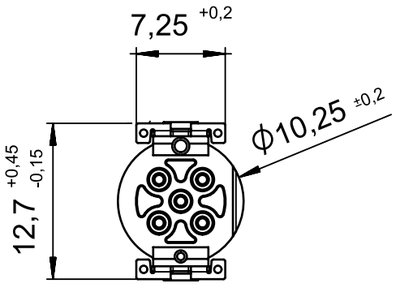
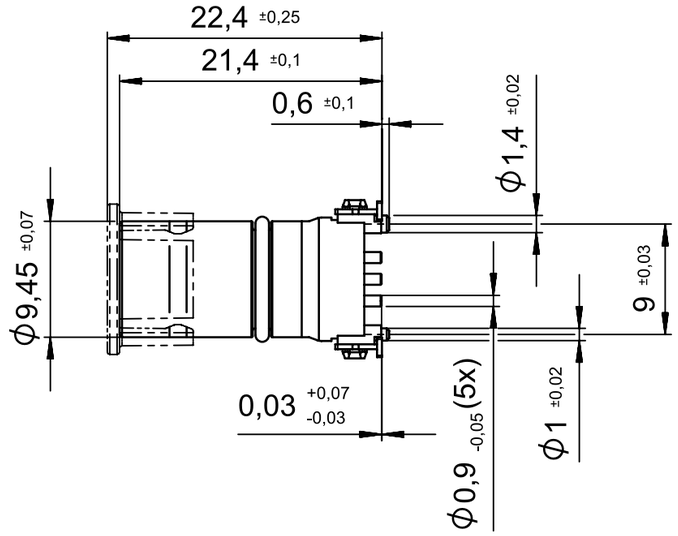
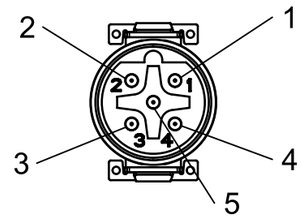
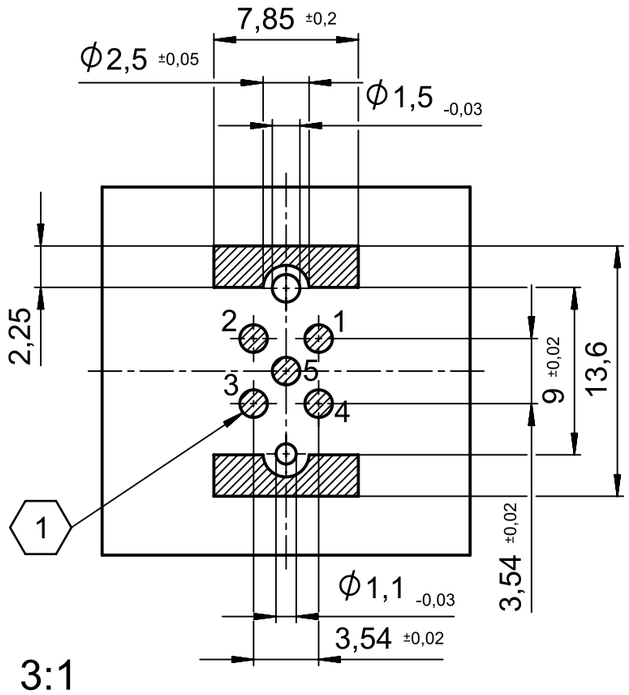




plug face male



PCB-layout
(advice)



3:1

Coplanarity of all contacts and anchor plate | ▱ | 0.1

Recommended solder paste thickness 150µm

(1) Further information on soldering process and recommended layout, see brochure "Connectors for SMT production"

- EN ISO 291 23/50

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